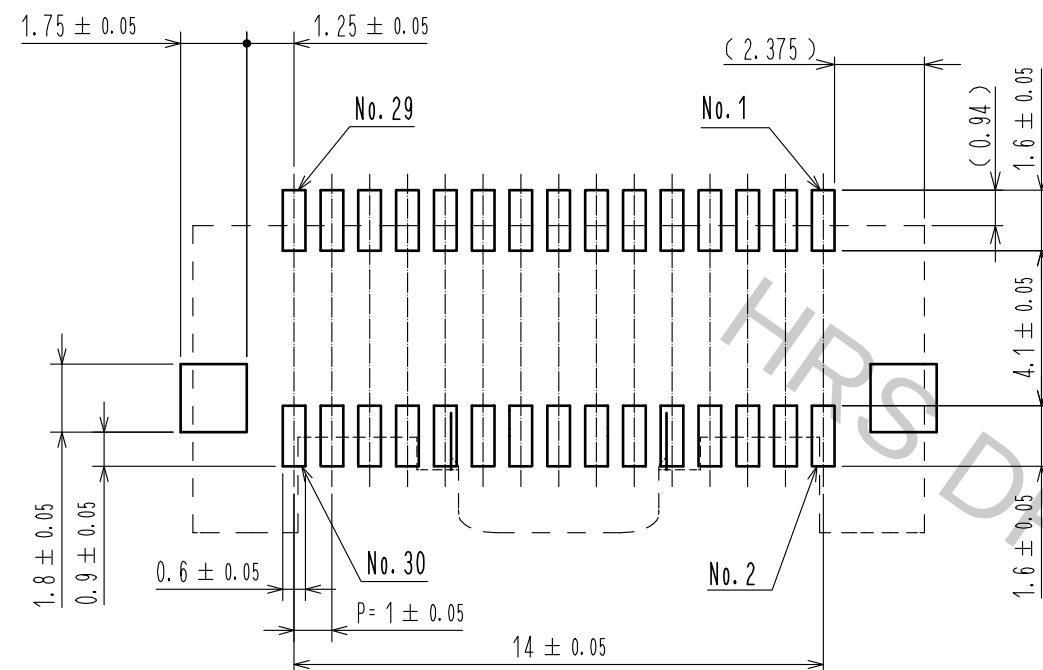


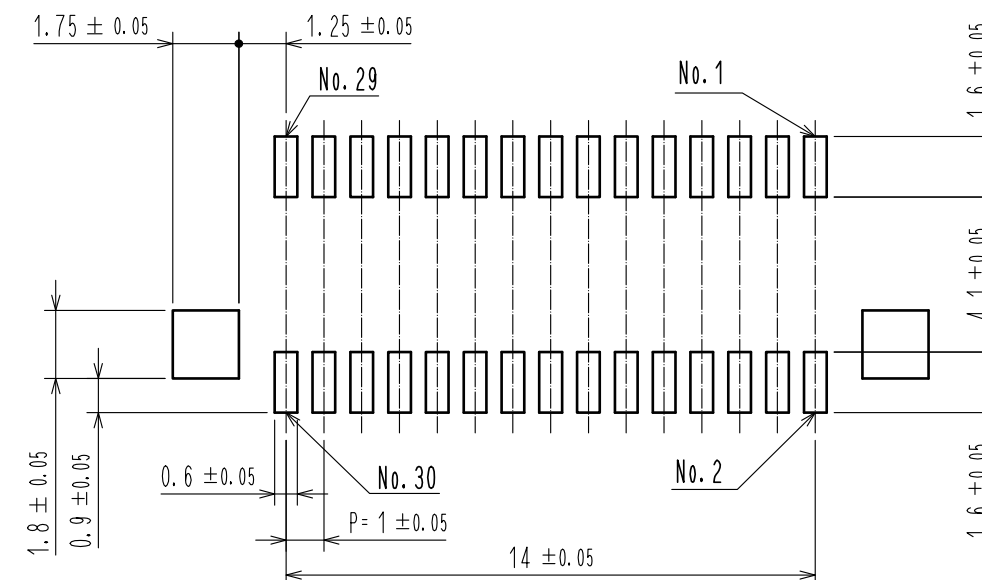
3	BRASS	CONTACT AREA: Au PLATING 0.05μm MIN LEAD AREA: Au PLATING 0.05μm MIN UNDER PLATING: Ni PLATING 1μm MIN			8	PS	REEL, BLACK				
2	BRASS	CONTACT AREA: Au PLATING 0.05μm MIN LEAD AREA: Au PLATING 0.05μm MIN UNDER PLATING: Ni PLATING 1μm MIN	7	POLYESTER	CLEAR						
			6	PS	CLEAR						
			5	STAINLESS STEEL	—						
1	LCP	BLACK, UL94V-0			4	BRASS	CONTACT AREA : Sn PLATING 1μm MIN UNDER PLATING : Ni PLATING 0.5μm MIN				
NO.	MATERIAL	FINISH . REMARKS				NO.	MATERIAL	FINISH . REMARKS			
UNITS mm		SCALE 5 : 1		COUNT 9	DESCRIPTION OF REVISIONS DIS-H-00001958		DESIGNED TS. MIYAKI	CHECKED TS. FUKUSHIMA	DATE 16. 08. 08		
 HIROSE ELECTRIC CO., LTD.		APPROVED : KI. AKIYAMA	11. 12. 26		DRAWING NO. EDC3-331316-01						
		CHECED : OM. MIYAMOTO	11. 12. 26		PART NO. DF50-30DP-1H(51)						
		DESIGNED : TT. OHSAKO	11. 12. 02		CODE NO. CL665-0015-2-51						
		DRAWN : TT. OHSAKO	11. 12. 02		 						

RECOMMENDED PCB LAYOUT (MOUNTING SURFACE SIDE) (FREE)

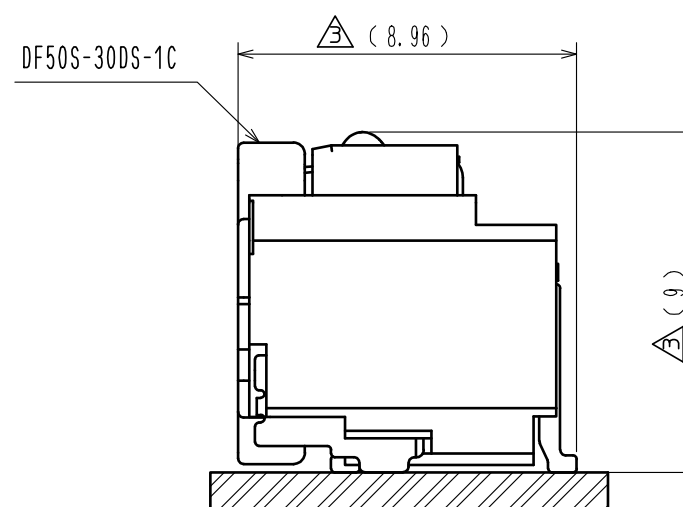
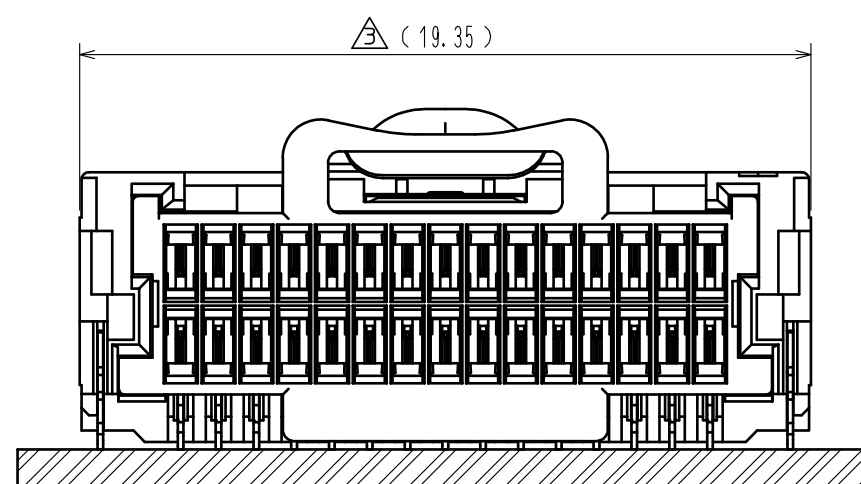


RECOMMENDED METAL MASK (FREE)

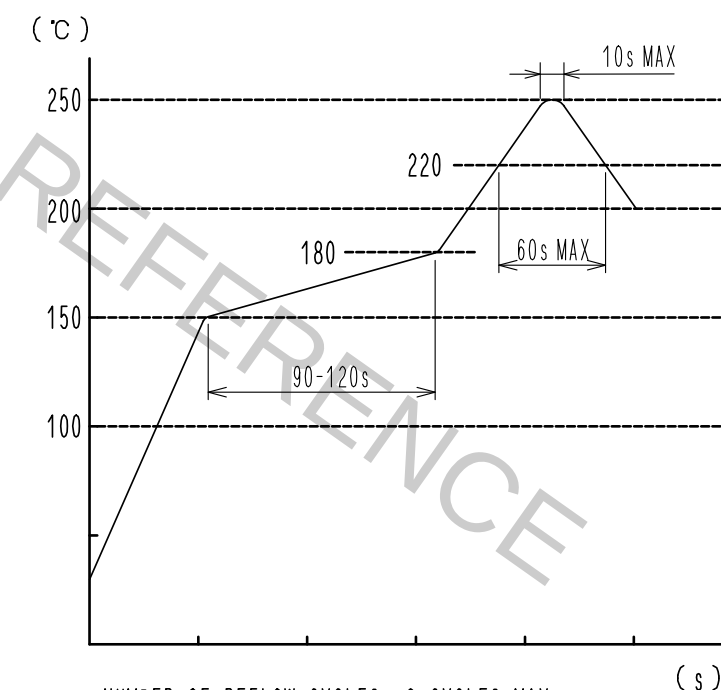
THICKNESS : 0.1mm
OPEN AREA RATIO:100%



MATING FIGURE (5 : 1)



REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
THE TEMPERATURE OF THIS PROFILE IS MEASURED ON THE LEAD TERMINAL.

WE RECOMMEND PERFORMING AN EVALUATION UNDER THE MOUNTING CONDITIONS YOU WILL BE USING BECAUSE IT COULD BE AFFECTED BY ANY CONDITION:TYPE OF SOLDER PASTE, SIZE OF PCB, MOUNTING MATERIAL etc..

HRS

DRAWING NO.	EDC3-331316-01
PART NO.	DF50-30DP-1H(51)
CODE NO.	CL665-0015-2-51

3/2/3

